

Welcome to O-leading

O-Leading strives to be your one stop solution partner in EMS supply chain, including PCB design , PCB fabrication and PCB assembly (PCBA).We provide some of the most advanced PCB technology, including HDI PCBs,multilayer PCBs, Rigid-Flexible PCBs.We can support from quick turn prototype to medium & mass Production. ([Multilayer pcb manufacturer china](#))

In general, our global customers are very impressed with our services:rapid response, competitive price and quality commitment.Providing more valuable technical service and overall solution is the way O-leading forward.

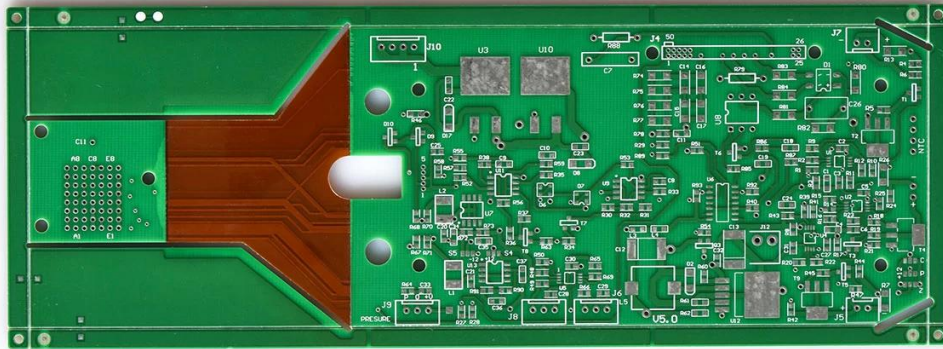
Looking to the future, O-leading will concentrate on the innovation and development of electronics manufacturing technology as always, and make persistent efforts on PCB & PCBA one-stop service to provide first-class services and create more value for our customers.

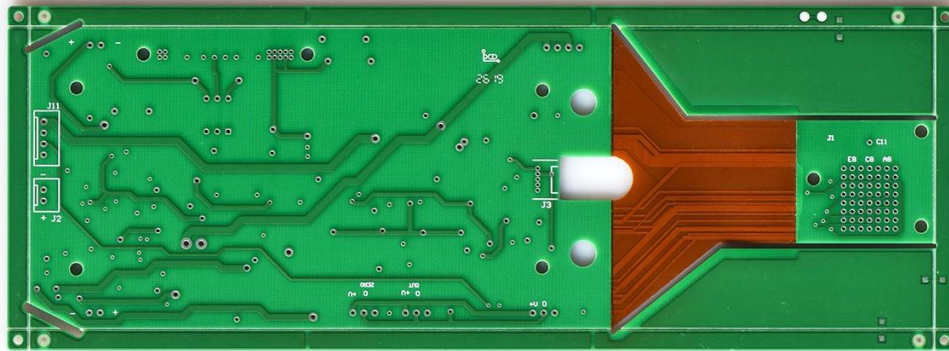
PLEASE CLICK THESE FOR MORE INFORMATION: [HDI PCB manufacturer china](#)

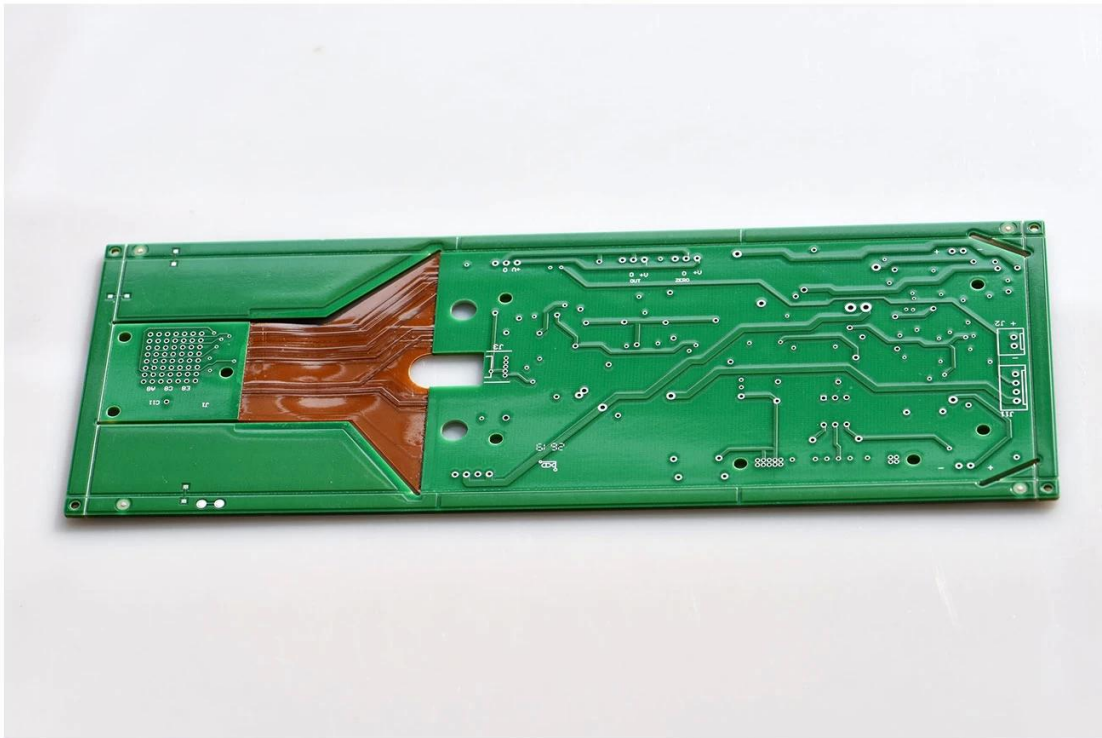
Product Description

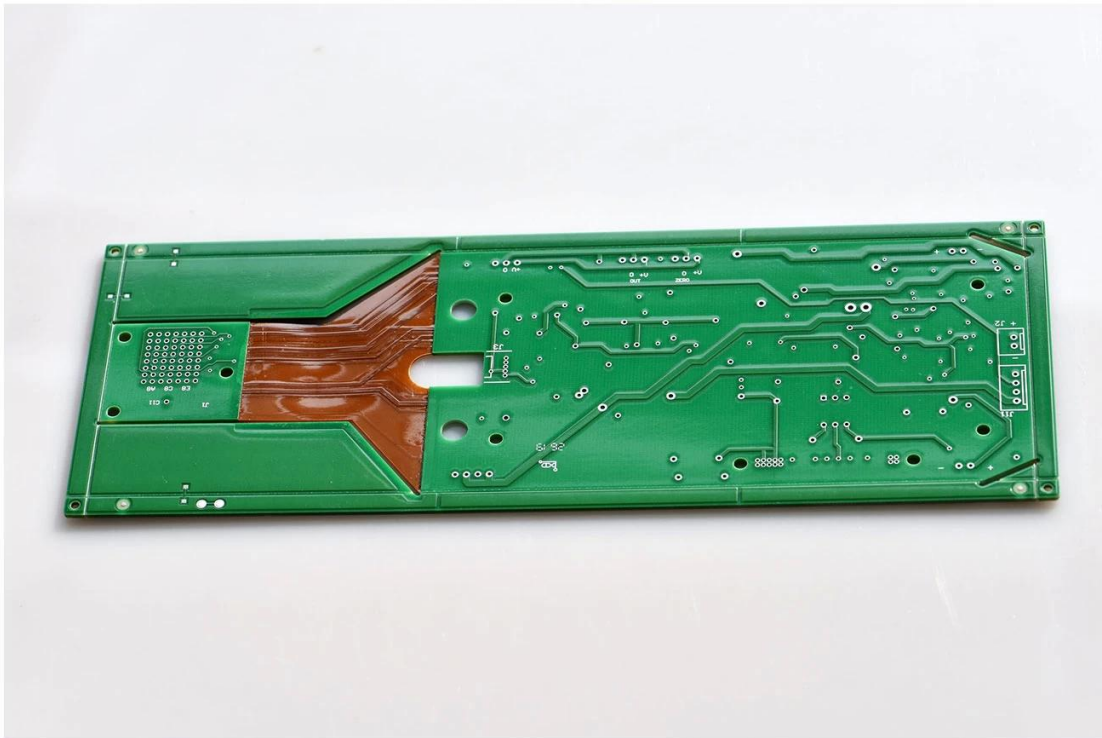
| | |
|----------------------------------|--|
| PCB P/N | RF560032Q_V5.0 |
| Layer Count | 4L (L1□L4 Rigid□L2□L3 Flex) |
| Material | FR-4 TG170 |
| Board thk | 1.2mm |
| copper thk | 1/H/H/1oz |
| Smallest hole size | 0.5MM |
| No. of holes (pcs) | 285 |
| line w/s | 12/12mil |
| Impedance control. Y / N (Tol %) | N |
| Surface Finishing | LF HASL Sn:1-40UM |
| Solder Mask Silkscreen | Green / White |
| Single board size | Dim X (mm):220.00;Dim Y (mm):80.00 |
| Panelisation | Dim X (mm):230.00;Dim Y (mm):90.00;No Of UPS:1 |
| Special:peelable mask: | N |
| Routing/Punching | CNC+V-CUT |

□









www.o-leading.com

Remote Control PCB solution

Our Team



Factory PCB



Automatic vacuum press machine



Drilling Machine



Pattern Plating Machine



Scrubbing Machine



Developing Machine



Routing Machine



High-speed flying probe machine

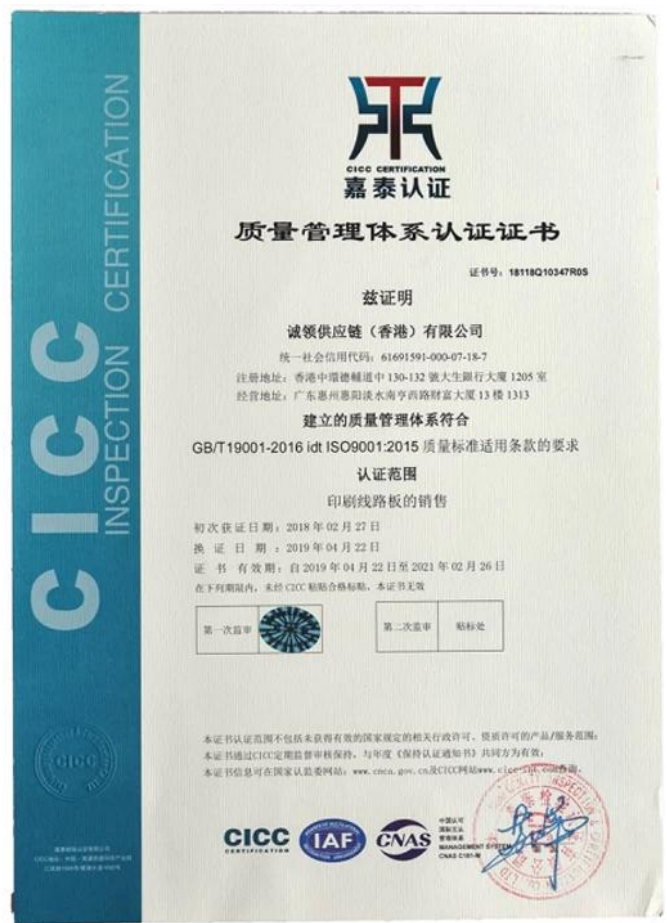


E-test Machine

Factory SMT



Certifications





Test Report

No. SZXEC1900530401

Date: 30 Mar 2019

Page 1 of 6

O-LEADING SUPPLY CHAIN (HK) CO., LIMITED

1313.FLOOR 13, FORTUNE BUILDING, DANSHUI TOWN, HUIYANG DISTRICT, HUIZHOU, GUANGDONG, CHINA

The following sample(s) was/were submitted and identified on behalf of the clients as : OSP

SGS Job No. : RP19-005089 - SZ

Date of Sample Received : 22 Mar 2019

Testing Period : 22 Mar 2019 - 30 Mar 2019

Test Requested : Selected test(s) as requested by client.

Test Method : Please refer to next page(s).

Test Results : Please refer to next page(s).

Conclusion : Based on the performed tests on submitted sample(s), the results of Lead, Mercury, Cadmium, Hexavalent chromium, Polybrominated biphenyls (PBBs), Polybrominated diphenyl ethers (PBDEs) and Phthalates such as Bis(2-ethylhexyl) phthalate (DEHP) , Butyl benzyl phthalate (BBP), Dibutyl phthalate (DBP) , and Diisobutyl phthalate (DIBP) comply with the limits as set by RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU.

Signed for and on behalf of
SGS-CSTC Standards Technical Services Co., Ltd. Shenzhen Branch

Tina

Tina Fan
Approved Signatory



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Test Report

No. SZXEC1900530401

Date: 30 Mar 2019

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Test Results :

Test Part Description :

| Specimen No. | SGS Sample ID | Description |
|--------------|------------------|-------------|
| SN1 | SZX19-005304.001 | Green"PCB" |

Remarks :

- (1) 1 mg/kg = 1 ppm = 0.0001%
- (2) MDL = Method Detection Limit
- (3) ND = Not Detected (< MDL)
- (4) "-" = Not Regulated

RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU

Test Method : With reference to IEC 62321-4:2013+A1:2017, IEC 62321-5:2013, IEC 62321-7-2:2017, IEC 62321-6:2015 and IEC 62321-8:2017, analyzed by ICP-OES, UV-Vis and GC-MS.

| Test item(s) | Limit | Unit | MDL | Q/Z |
|------------------------------|-------|-------|-----|-----|
| Cadmium (Cd) | 100 | mg/kg | 2 | ND |
| Lead (Pb) | 1,000 | mg/kg | 2 | 8 |
| Mercury (Hg) | 1,000 | mg/kg | 2 | ND |
| Hexavalent Chromium (Cr(VI)) | 1,000 | mg/kg | 8 | ND |
| Sum of PBBs | 1,000 | mg/kg | - | ND |
| Monobromobiphenyl | - | mg/kg | 5 | ND |
| Dibromobiphenyl | - | mg/kg | 5 | ND |
| Tribromobiphenyl | - | mg/kg | 5 | ND |
| Tetrabromobiphenyl | - | mg/kg | 5 | ND |
| Pentabromobiphenyl | - | mg/kg | 5 | ND |
| Hexabromobiphenyl | - | mg/kg | 5 | ND |
| Heptabromobiphenyl | - | mg/kg | 5 | ND |
| Octabromobiphenyl | - | mg/kg | 5 | ND |
| Nonabromobiphenyl | - | mg/kg | 5 | ND |
| Decabromobiphenyl | - | mg/kg | 5 | ND |
| Sum of PBDEs | 1,000 | mg/kg | - | ND |
| Monobromodiphenyl ether | - | mg/kg | 5 | ND |
| Dibromodiphenyl ether | - | mg/kg | 5 | ND |
| Tribromodiphenyl ether | - | mg/kg | 5 | ND |
| Tetrabromodiphenyl ether | - | mg/kg | 5 | ND |
| Pentabromodiphenyl ether | - | mg/kg | 5 | ND |



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ZPMV2.E490354 - WIRING, PRINTED - COMPONENT

Wiring, Printed - Component

See General Information for Wiring, Printed - Component

O-LEADING SUPPLY CHAIN (HK) CO LTD

E490354

ROOM 1205, 12/F
TAI SANG BANK BLDG
130-132 DES VOEUS ROAD
CENTRAL, HONG KONG

| Type | Cond Width | | Cond Thk | SS/DSO | Max Area | | Max Solder | | Max Oper | | Meets | | C |
|--|---------------|---------------|----------------------|--------|------------|--------|------------|-------|----------|-----|-------|---|---|
| | Min | Edge | | | Diam | Limits | Temp | Flame | UL796 | DSR | | | |
| | mm(in) | mm(in) | mic(mil) | | mm(in) | C | sec | C | Class | | | | I |
| Multilayer (mass laminate) printed wiring boards. | | | | | | | | | | | | | |
| O-LEADING-401 | 0.1 (0.004) | 0.3 (0.012) | 34 (1.34) | DS | 12.7 (0.5) | 260 | 10 | 130 | V-0 | - | - | - | - |
| O-LEADING-407 | 0.08 (0.003) | 0.2 (0.008) | 17 (0.67) | DS | 9.7 (0.4) | 260 | 10 | 130 | V-0 | All | - | - | - |
| Multilayer printed wiring boards. | | | | | | | | | | | | | |
| O-LEADING-408 | 0.125 (0.005) | 0.125 (0.005) | 12 (0.47) Int:136 | DS | 50.8 (2.0) | 280 | 20 | 130 | V-0 | All | * | - | - |
| Single layer printed wiring boards. | | | | | | | | | | | | | |
| O-LEADING-002 | 0.38 (0.015) | 1.14 (0.045) | 34 (1.34) | SS | 19.1 (0.8) | 260 | 10 | 105 | V-0 | All | - | - | - |
| O-LEADING-003 | 0.38 (0.015) | 1.14 (0.045) | 34 (1.34) | SS | 19.1 (0.8) | 260 | 10 | 130 | V-0 | ▲ | - | - | - |
| O-LEADING-033 | 0.15 (0.006) | 0.3 (0.012) | 34 (1.34) | SS | 25.4 (1.0) | 260 | 10 | 120 | V-0 | All | - | - | - |
| O-LEADING-205 | 0.1 (0.004) | 0.3 (0.012) | 34 (1.34) | DS | 69.6 (2.7) | 260 | 10 | 130 | V-0 | All | - | - | - |
| O-LEADING-206 | 0.15 (0.006) | 0.33 (0.013) | 17 (0.67) | DS | 69.6 (2.7) | 260 | 10 | 130 | V-0 | All | - | - | - |
| O-LEADING-D01 | 0.14 (0.006) | 0.15 (0.006) | 33 (1.30) | DS | 25.4 (1.0) | 260 | 10 | 130 | V-0 | All | * | - | - |
| O-LEADING-S01 | 0.25 (0.010) | 0.25 (0.010) | 17 (0.67) | SS | 25.4 (1.0) | 260 | 4 | 130 | V-0 | All | * | - | - |

WIRING, PRINTED - COMPONENT | UL Product iQ

| | | | | | | | | | | | | | |
|----------------------|--------------|--------------|-----------|----|------------|-----|---|-----|-----|-----|---|---|---|
| O-LEADING-S02 | 0.2 (0.008) | 0.2 (0.008) | 17 (0.67) | SS | 25.4 (1.0) | 260 | 4 | 130 | HB | ▲ | * | - | - |
| O-LEADING-S03 | 0.25 (0.010) | 0.25 (0.010) | 34 (1.34) | SS | 25.4 (1.0) | 260 | 4 | 130 | V-0 | All | * | - | - |

* - CTI marking is optional and may be marked on the printed wiring board.

Marking: Company name or file number and type designation. May be followed by a suffix to denote factory identification or burning test classification.

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Packaging & Delivery

Shipping service



| Quick Turn Lead Time | | |
|----------------------|----------|---------------------|
| Layer Count: | Lead Tim | Special Requirement |
| 1L/2L | 2-3days | 24 Hours,48 Hours |
| 4L | 3-4days | 48 Hours |
| 6L | 4-5days | 72 Hours |
| 8L | 5-6days | NA |
| 10L | 6-7days | NA |
| 12L | 7-8days | NA |
| 14L | 8-9days | NA |

| Standard Lead Time | | |
|--------------------|------------------|------------------------|
| Layer Count: | Sample Lead Time | Volume order lead time |
| 2L | 4 days | 10 days |
| 4L | 5 days | 11 days |
| 6L | 6 days | 12 days |
| 8L | 8 days | 14 days |
| 10L | 10 days | 16 days |
| 12L | 12 days | 18 days |
| 14L | 14 days | 20 days |
| 16-32L | 18 days | 24 days |

Process Capability

PCB Production Capabilities

Layer Count: 1Layer-32Layer

Finished copper thickness□ 1/3oz-12oz

Min Line width/spacing internal□ 3.0mil/3.0mil

Min Line width/spacing external: 4.0mil/4.0mil

Max Aspect Ratio: 10:1

Board thickness□ 0.2mm-5.0mm

Max Panel size(inches): 635*1500mm

Minimum Drilled Hole Size: 4mil

Plated Hole Tolerance: +/-3mil

Blind/Buried Vias (All Types): YES

Via Fill(Conductive,Non-Conductive): YES

Base Material: FR-4,FR-4high Tg.Halogen free material,Rogers,Aluminium base,Polyimide,
Heavy Copper

Surface finishes: HASL,OSP,ENIG,HAL-LF,Immersion silver,Immersion Tin,Gold fingers,Carbon ink

SMT Production Capabilities

PCB Material: FR-4,CEM-1,CEM-3,Aluminum-based board

Max PCB size: 510x460mm

Min PCB size□50x50mm

PCB Thickness□0.5mm-4.5mm

Board thickness□0.5-4mm

Min Components size: 0201

Standard chip size component: 0603 and larger

Component max height□15mm

Min lead pitch: 0.3mm

Min BGA ball pitch:0.4mm

Placement precision: +/-0.03mm